

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.44881	100.0	4.8
			<b>Subtotal</b>	<b>0.44881</b>	<b>100</b>	<b>4.8</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03749	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01125	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03749	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.4083	99.77	400.0777
			<b>Subtotal</b>	<b>37.49453</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84098	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.91871	10.0	63.3
	Filler	Silica fused	60676-86-0	50.30907	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11837	0.2	1.266
			<b>Subtotal</b>	<b>59.18713</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33756	100.0	25
			<b>Subtotal</b>	<b>2.33756</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01394	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.2188	100.0	2.34
			<b>Subtotal</b>	<b>0.23274</b>	<b>200</b>	<b>2.4891</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00598	2.0	0.064
	Lead alloy	Silver (Ag)	7440-22-4	0.00748	2.5	0.08
	Lead alloy	Lead (Pb)	7439-92-1	0.28574	95.5	3.056
			<b>Subtotal</b>	<b>0.2992</b>	<b>100</b>	<b>3.2</b>
			<b>Total</b>	<b>99.99997</b>	<b>100</b>	<b>1069.4891</b>

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